

Excellent Integrated System Limited

Stocking Distributor

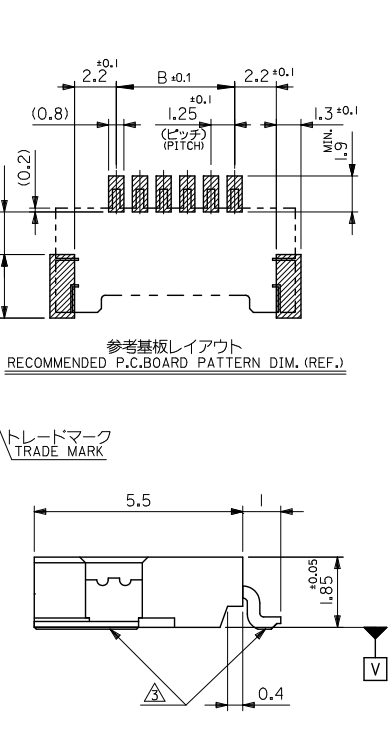
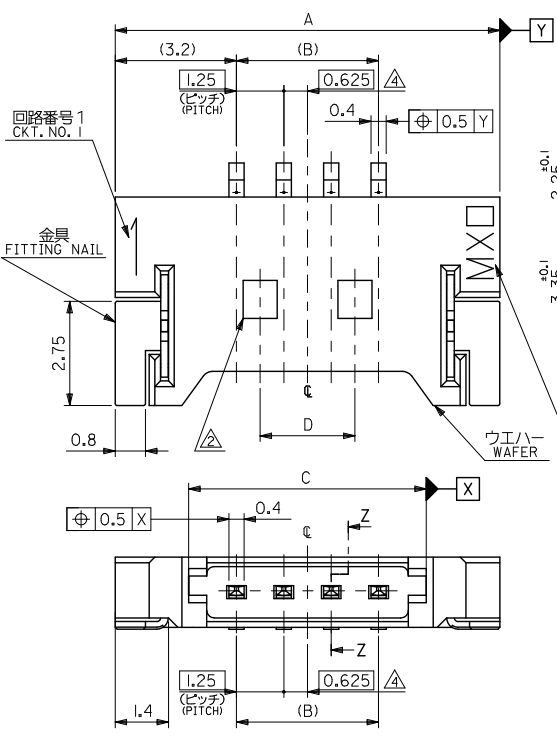
Click to view price, real time Inventory, Delivery & Lifecycle Information:

[Molex Connector Corporation](#)
[0537802070](#)

For any questions, you can email us directly:

sales@integrated-circuit.com

10 9 8 7 6 5 4 3 2 1



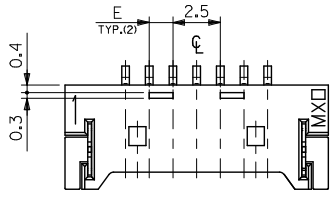
注記 NOTES

- 嵌合相手: 51146 シリーズ
MATES WITH: 51146 SERIES
- ロック窓は2、3極品は1箇所、4極品以上は2箇所とする。
LOCKING WINDOW: ONE PLACE FOR 2 AND 3 CIRCUIT PRODUCTS AND TWO PLACES FOR MORE THAN 3 CIRCUIT PRODUCTS.
- 基準面[V]からのソルダーテールと金具の半田付け面のズレ量は、上方向に0.05MAX、下方向0.15MAX、とし、20極以下の相互のパラッキ量は0.1MAX、とする。
MISALIGNMENT OF SOLDER TAIL AND FITTING NAIL FROM [V]: UPPER DIRECTION 0.05MAX, LOWER DIRECTION 0.15MAX, OFFSET BETWEEN UPPER AND LOWER 0.1MAX. (UNDER 20 CKTS.)
- 偶数極の製品に適用。
APPLY EVEN CIRCUIT PRODUCTS.
- 材質 MATERIAL
ウエハー WAFER: PPS, UL94V-0
ピン: リン青銅 PIN: PHOSPHOR BRONZE
コンタクト部: 金メッキ 0.2 マイクロメートル以上
CONTACT AREA: GOLD 0.2 MICROMETER MINIMUM
テール部: 錫メッキ 3.0 マイクロメートル以上
TAIL AREA: TIN 3.0 MICROMETER MINIMUM
下地メッキ: ニッケルメッキ 1.0 マイクロメートル以上
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM
金具: リン青銅 FITTING NAIL: PHOSPHOR BRONZE
錫メッキ 3.0 マイクロメートル以上
TIN 3.0 MICROMETER MINIMUM
下地メッキ: ニッケルメッキ 1.0 マイクロメートル以上
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM
- 本製品は 53780-**10/-**18 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53780-**10/-**18.
- ELV及のRoHS適合品
ELV & ROHS COMPLIANT.

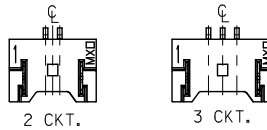
16.25	22.5	38.77	36.25	42.65	53780-3070	30	
8.75	22.5	26.27	23.75	30.15		-2070 20	
7.5	20	23.77	21.25	27.65		-1870 18	
6.25	16.25	20.02	17.5	23.9		-1570 15	
5	15	18.77	16.25	22.65		-1470 14	
3.75	12.5	16.27	13.75	20.15		-1270 12	
2.5	10	13.77	11.25	17.65		-1070 10	
2.5	8.75	12.52	10	16.4		-0970 9	
1.25	7.5	11.27	8.75	15.15		-0870 8	
1.25	6.25	10.02	7.5	13.9		-0770 7	
—	5	8.77	6.25	12.65		-0670 6	
—	3.75	7.52	5	11.4		-0570 5	
—	2.5	6.27	3.75	10.15		-0470 4	
—	—	5.02	2.5	8.9		-0370 3	
—	—	3.77	1.25	7.65		-0270 2	
						53780-0270	2
E	D	C	B	A	EMBOSSED PACKAGE CKT.		
						オーダー番号 ORDER No.	極数

REVISED EC NO. J2010-1927 DRAWN: SKUROSE 2010/03/25 CHKD: KAKAWA 2010/03/26 APPR: NIKITA 2010/03/29	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	CONNECTOR SERIES NO.	53780-**19	
	10 UNDER	± 0.2	MM ONLY	---	METRIC			
	10 OVER 30 UNDER	± 0.25						
	30 OVER	± 0.3						
	ANGULAR	± 3 °						
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							
			DRAWN BY	DATE	TITLE			
			T. UENO	'04/04/15	1.25 W/B CONN WAFER ASSY FOR SMT			
			CHECKED BY	DATE				
			M. SASAO	'04/04/15				
			APPROVED BY	DATE				
			M. SASAO	'04/04/15				
			MATERIAL NO.	DOCUMENT NO.				
			SEE CHART	SD-53780-003				
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
			SIZE				SHEET NO.	
			A3				1 OF 2	

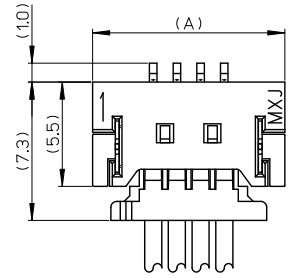
10 9 8 7 6 5 4 3 2 1



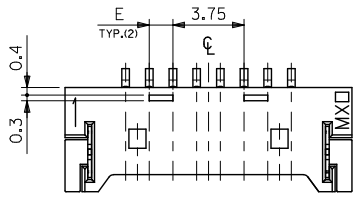
7~19 極の奇数極に適用
APPLY FOR ODD CIRCUITS OF 7~19



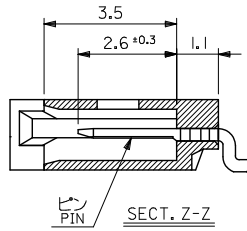
ロック形状図
LOCK CONFIGURATION



嵌合図 (SCALE 5:1)
MATED CONNECTORS (SCALE 5:1)



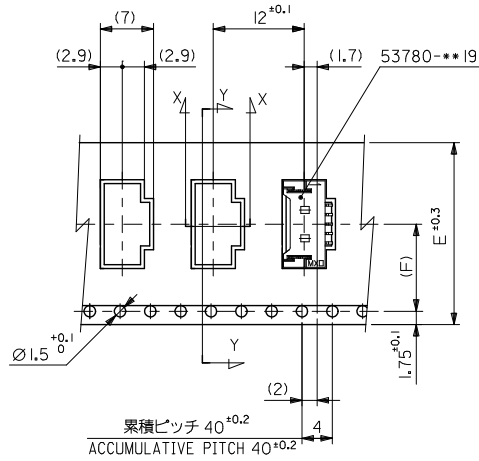
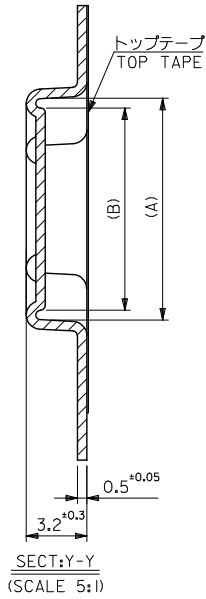
8~30 極の偶数極に適用
APPLY FOR EVEN CIRCUITS OF 8~30



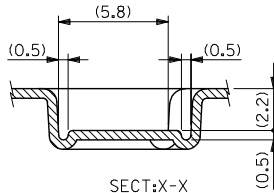
SECT. Z-Z

REVISED IEC NO. J2010-1927 DRAWN: SKUROSE 2010/03/25 CHIKIDAKAWA 2010/03/26 APPR: NIKITA 2010/03/29	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		CONNECTOR SERIES NO. 53780-***19
	10 UNDER	± 0.2	DRAWN BY	T. UENO	SCALE ---
	10 OVER	30 UNDER	CHECKED BY	M. SASAO	DESIGN UNITS METRIC
	30 OVER	± 0.3	DATE	'04/04/15	THIRD ANGLE PROJECTION
	ANGULAR ± 3 °		APPROVED BY	M. SASAO	TITLE
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.	SEE CHART	MOLEX INCORPORATED	1.25 W/B CONN WAFER ASSY FOR SMT
			SIZE	A3	DOCUMENT NO. SD-53780-003
					SHEET NO. 2 OF 2

10 9 8 7 6 5 4 3 2 1



引き出し方向
PULL OUT DIRECTION

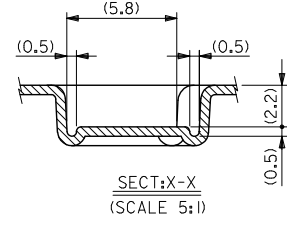
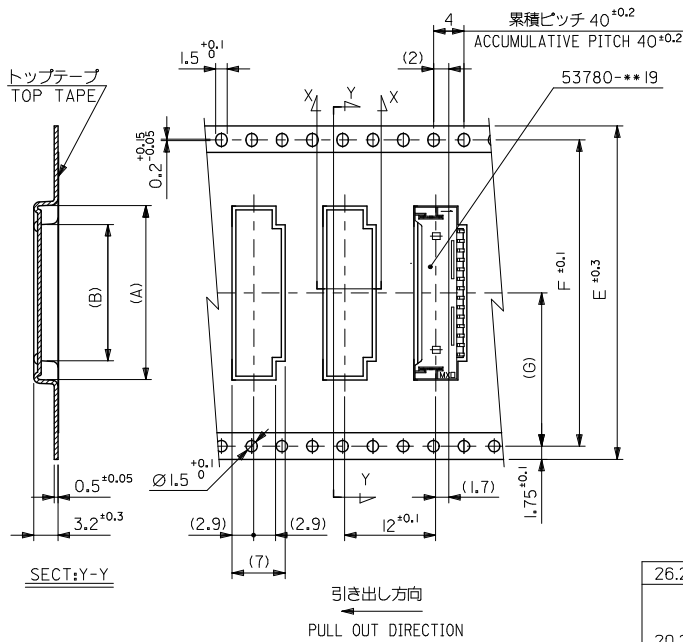


11.5	24	29.4	25.4	11.75	16.7	53780-0970	9
				10.5	15.45	53780-0870	8
				9.25	14.2	53780-0770	7
				8	12.95	53780-0670	6
7.5	16	21.4	17.4	6.75	11.7	53780-0570	5
				5.5	10.45	53780-0470	4
				4.25	9.2	53780-0370	3
(F)	E	D	C	(B)	(A)	MATERIAL NO.	継電 CKT.

MODEL NO. 53780-***70
DESIGN UNITS METRIC
THIRD ANGLE PROJECTION

REVISED EC NO. J2010-0021 DRAWN/TAKASAKI 2009/07/07 CHKD/MHAYASHI 2009/07/08 APPR./MUKITA 2009/07/08	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	TITLE 1.25 W/B WAFER ASSY EMBOSSSED TAPE PACKAGE
	10 UNDER	± 0.2	DRAWN BY T. UENO	DATE '04/04/15	MOLEX INCORPORATED
	10 OVER 30 UNDER	± 0.25	CHECKED BY M. SASAO	DATE '04/04/15	
	30 OVER	± 0.3	APPROVED BY M. SASAO	DATE '04/04/15	DOCUMENT NO. SD-53780-004
	ANGULAR ± 3 °		MATERIAL NO. SEE CHART		SHEET NO. 2 OF 3
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

10 9 8 7 6 5 4 3 2 1



26.2	52.4	56	61.4	57.4	38	42.95	53780-3070	30
					25.5	30.45	53780-2070	20
					25.5	27.95	53780-1870	18
20.2	40.4	44	49.4	45.4	19.25	24.2	53780-1570	15
					18	22.95	53780-1470	14
					15.5	20.45	53780-1270	12
14.2	28.4	32	37.4	33.4	13	17.95	53780-1070	10
(G)	F	E キャリアテープ幅 CARRIER TAPE WIDTH	D	C	(B)	(A)	MATERIAL NO.	極数 CKT.

REVISED EC NO. J2010-0021 DRAWN BY DR. N. TAKASAKI 2009/07/07 CHECKED BY CHIKO. HAYASHI 2009/07/08 APPROVED BY APPR. N. ITO 2009/07/08	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	MODEL NO. 53780-***70
	10 UNDER	± 0.2	DRAWN BY T. UENO	DATE '04/04/15	TITLE 1.25 W/B WAFER ASSY EMBOSSED TAPE PACKAGE	DESIGN UNITS METRIC
	10 OVER 30 UNDER	± 0.25	CHECKED BY M. SASAO	DATE '04/04/15	MATERIAL NO.	THIRD ANGLE PROJECTION
	30 OVER	± 0.3	APPROVED BY M. SASAO	DATE '04/04/15	DOCUMENT NO. SD-53780-004	SHEET NO. 3 OF 3
ANGULAR ± 3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION